

Abstract of the Disclosure

A connective structure is formed by first depositing an insulator over a planarized surface. A trench is etched in the insulator. A barrier layer is deposited on the insulator. A seed layer is deposited on the barrier layer. The barrier layer and seed layer are selectively removed from areas of the insulator leaving an exposed seed area. A conductor is deposited on the exposed seed area. As many of these connective structures as desired may be stacked in an integrated circuit structure.

"Express Mail" mailing label number: EM287049297US

Date of Deposit: MARCH 1, 1999
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